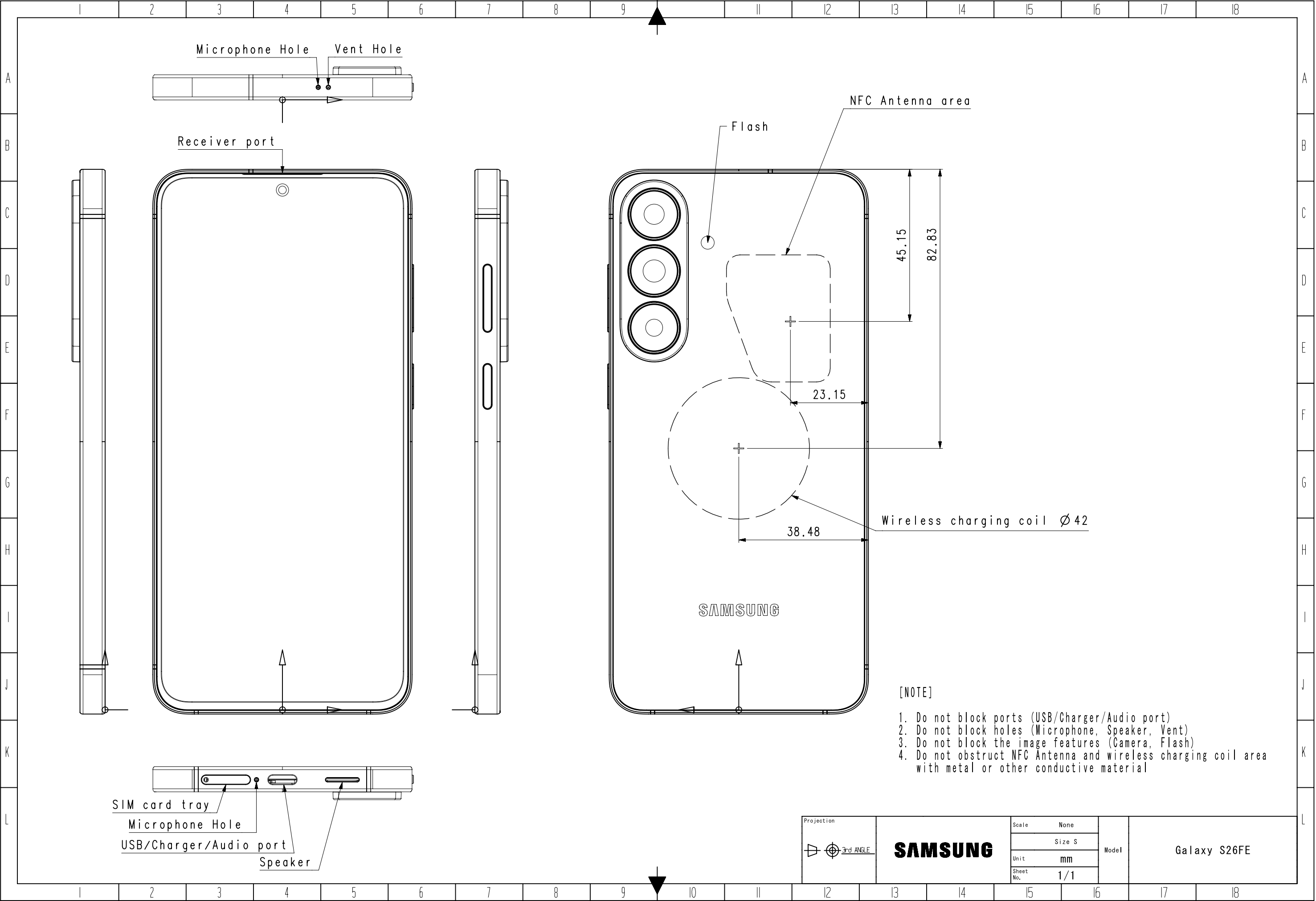




- [NOTE]
- 1. Do not block ports (USB/Charger/Audio port)
 - 2. Do not block holes (Microphone, Speaker, Vent)
 - 3. Do not block the image features (Camera, Flash)
 - 4. Do not obstruct NFC Antenna and wireless charging coil area with metal or other conductive material

Projection		Scale	None	Model	Galaxy S26FE	
 3rd ANGLE	SAMSUNG	Size				S
		Unit				mm
		Sheet No.				1 / 1

S26FE Series reference design guide : Magnet Position & Cover Thickness

□ MPP Cover Guide #1 for R14

① Magnet Position

- There is an offset between the magnet center and the device center

② Cover Thickness ($d_{z,1}$: 1.6T ~ 1.9T)

$$(d_{z,1} = d_{z,2} + d_m + d_{z,3} + d_{z,air})$$

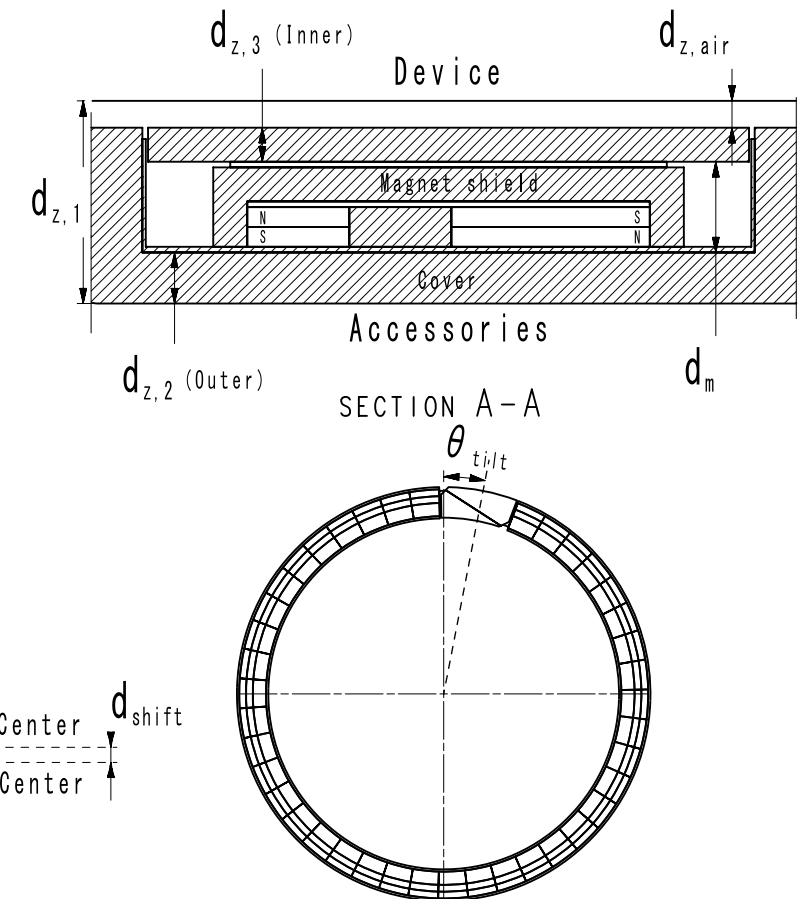
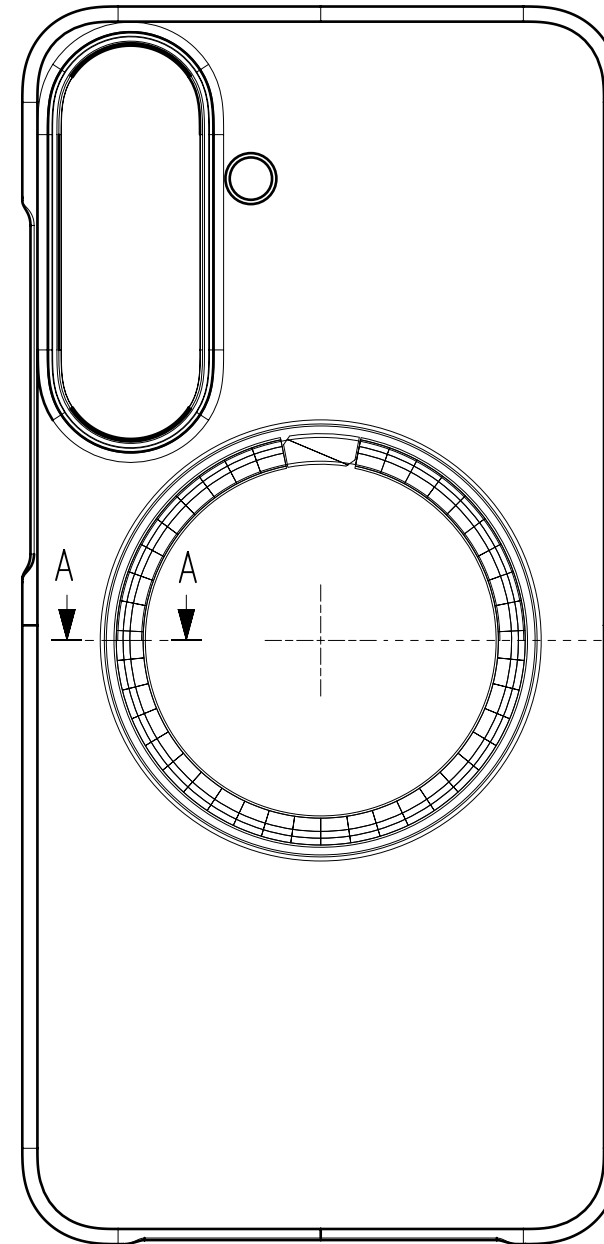
- R14 Series devices are designed for Qi2 standard within the 1.6T ~ 1.9T range.
- $d_{z,1}$ includes the air gap between the device and cover.
- The sum of $d_{z,air}$ and $d_{z,3}$ shall be 0.35T, and adjustable within this range.

③ Thickness of Magnet + Cover Surface ($d_{z,2}$: 0.5T ~ 0.7T)

- Design required within 0.5T to 0.7T to maintain ideal magnetic coupling with accessories.
- Maximum 0.7T to be maintained to control pull force / shear force.

④ Tilt Angle of 'A' Magnet (θ_{tilt})

- 'A' magnet is located between SPCC slit; see 'Magnet Characteristics' page for details.
- θ_{tilt} may vary depending on the hall IC position of each model.



□ Key Dimension

	S26 Ultra	S26 Plus	S26	S26FE
θ_{tilt} (Tol $\pm 1^\circ$)	0°	←	←	←
d_{shift}	4.5mm	3mm	6.1mm	2mm
$d_{z,1}$	1.5~1.9mm	←	←	1.6~1.9mm (Silicone:1.9mm)
$d_{z,2}$	0.4 ~ 0.8mm (Max 0.8mm, minus tol. only)	←	←	0.5~0.7mm (Silicone:0.7mm)
$d_{z,3} + d_{z,air}$	0.35mm	←	←	

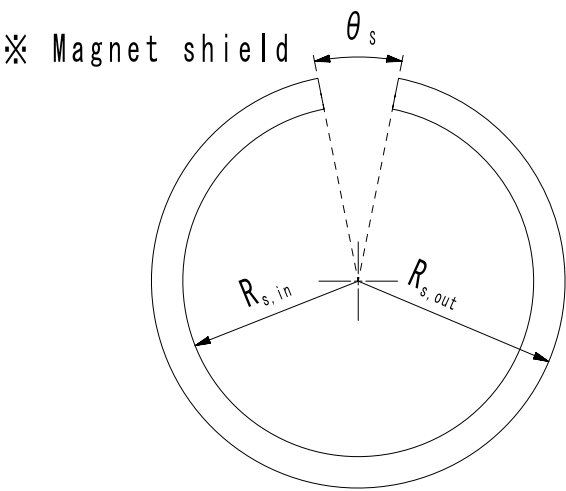
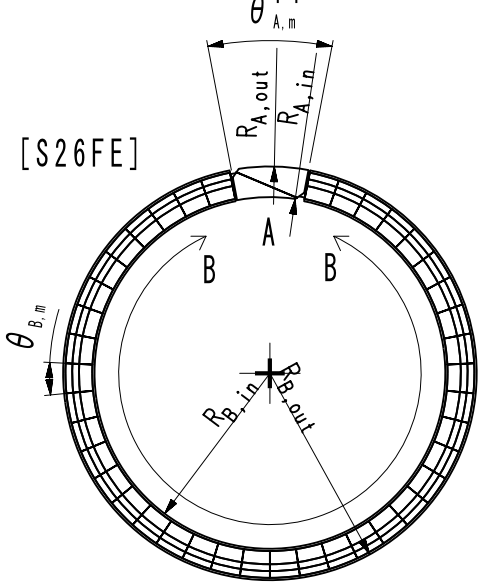
※ Tolerance : $\pm 0.05\text{mm}$, unless otherwise specified

Projection	 3rd ANGLE	Scale		None	Model	Galaxy S26FE
		Size		S		
		Unit		mm		
		Sheet No.		1 / 1		

S26FE Series reference design guide : Magnet Characteristics

MPP Cover Guide #2 for R14

- 'A' Magnet is designed to prevent bridging in SPCC slit : Epoxy Coating & $\theta_{A,m}$ (21.5°)
- Magnetized zone : Magnetized zone of 'B' Magnet is asymmetric
- 'A' and 'B' Magnet have different thicknesses : $T_{m,A}$ (0.7T), $T_{m,B}$ (0.35T)
- Magnet Shield Thickness and Material : T_s (0.3T), SPCC (EGI)
- Total Thickness : T_{tt} (0.75T) includes adshesive applied to the cover

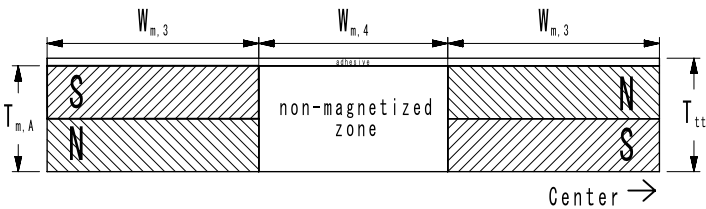


Key Dimension (Magnet Shield)

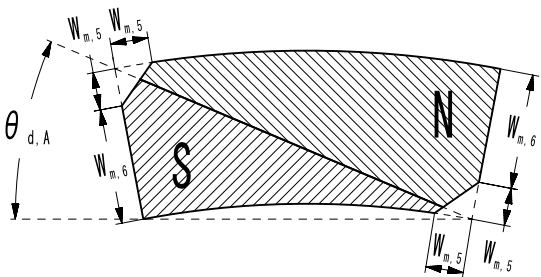
Material	SPCC (EGI)
θ_s	22.5°
$R_{s,in}$	23.2 mm
$R_{s,out}$	27.35 mm
Magnet Shield Width ($R_{s,out}-R_{s,in}$)	4.15 mm
T_s	0.3 mm

'A' Magnet Magnetization Pattern

S26U (Side View)

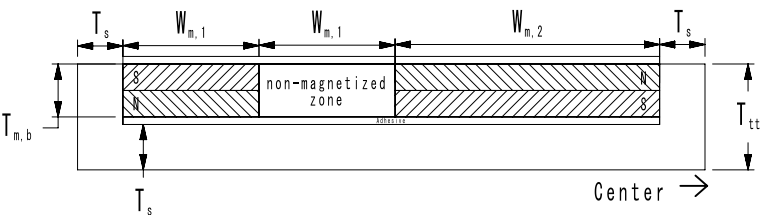


S26+, S26, S26FE (TOP View)



**Careful attention to the direction of insertion is required

'B' Magnet Magnetization Pattern



Key Dimension (Magnet)

Magnet Grade (Surface Finish)	A : N35SH (Epoxy) B : N45SH (Ni)
$\theta_{A,m} / \theta_{B,m}$	A : 21.5° / B : 8.4°
$R_{A,in} / R_{A,out}$	23.3 / 27.35 mm
$R_{B,in} / R_{B,out}$	23.5 / 27.05 mm
$W_{m,1}$	0.9 mm
$W_{m,2}$	1.75 mm
$W_{m,3}$	1.4 mm
$W_{m,4}$	1.25 mm
$W_{m,5}$	1.00 mm
$W_{m,6}$	3.05 mm
$\theta_{d,A}$	22.8°
Magnet Width	A : 4.05mm B : 3.55mm
T_{adh} (magnet ↔ cover) T_{adh} (magnet ↔ SPCC)	0.05 mm
$T_{m,A}$	0.7 mm/0.85mm(Silicone)
$T_{m,B}$	0.35 mm/0.5mm(Silicone)
T_{tt}	0.75 mm/0.9mm(Silicone)

※ Tolerance : ±0.05mm, unless otherwise specified

Projection 3rd ANGLE	SAMSUNG	Scale	None	Model	Galaxy S26FE
		Size	S		
		Unit	mm		
		Sheet No.	1/1		